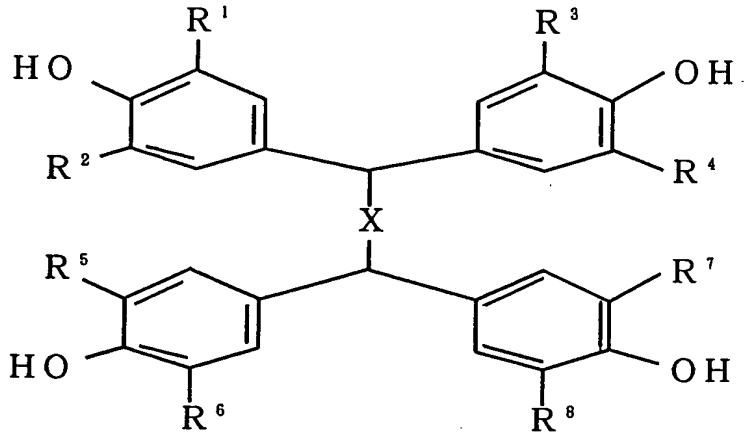
What is claimed is:

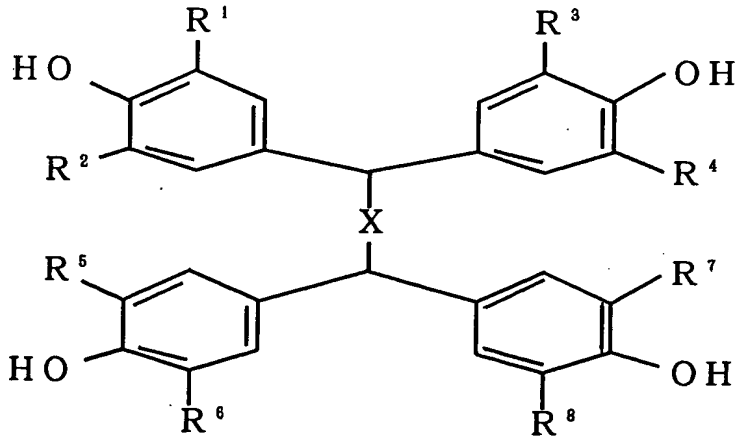
1. Curatives for epoxy resins characterized by being a clathrate comprising a tetrakisphenol compound represented by a general formula [I];



〔I〕

wherein X represents $(CH_2)n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy, and a compound which reacts with the epoxy group of an epoxy resin to cure the resin.

2. Curing accelerators for epoxy resins characterized by being a clathrate comprising a tetrakisphenol compound represented by a general formula [I];

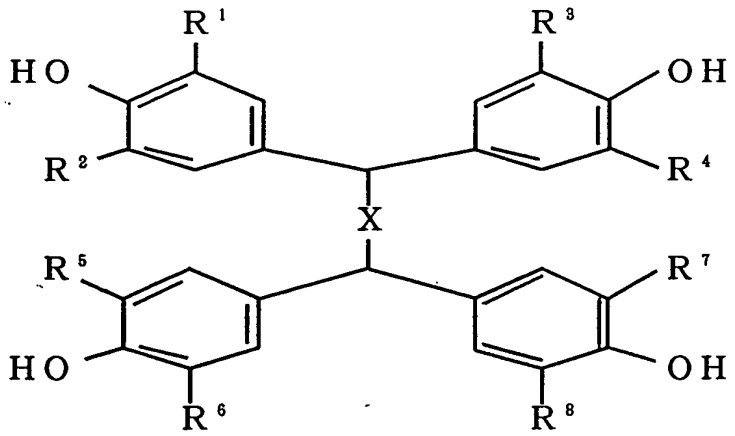


〔I〕

wherein X represents $(CH_2)n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy, and a compound accelerating the curing of a compound which reacts with the epoxy group of an epoxy resin to cure the resin.

3. Epoxy resin compositions characterized by containing the clathrate comprising a tetrakisphenol compound represented by a general formula [I] and a compound which reacts with the epoxy group of an epoxy resin to cure the resin according to claim 1 and/or the clathrate comprising a tetrakisphenol compound represented by a general formula [I] and a compound accelerating the curing of a compound which reacts with the epoxy group of an epoxy resin to cure the resin according to claim 2.

4. Epoxy resin compositions characterized by containing a curative which reacts with the epoxy group of an epoxy resin to cure the resin and a tetrakisphenol compound represented by a general formula [I];



〔I〕

wherein X represents $(CH_2)n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy, in an amount of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

5. Epoxy resin compositions characterized by containing the clathrate according to claim 1 which which comprises a tetrakisphenol compound represented by a general formula [I] and a compound which reacts with the epoxy group of an epoxy resin to cure the resin and the

clathrate according to claim 2 which comprises a tetrakisphenol compound represented by a general formula [I] and a compound accelerating the curing of a compound which reacts with the epoxy group of an epoxy resin to cure the resin, wherein the content of the clathrate in the resin composition is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups, respectively.